



Products

Design Resources

Technical Info

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---Useful Links---

RoHS

Quick Reference

Search by part #



Check distributor part inventory



Products

Browse Heat sinks

- By Device -

- By Product Line -

- Attachment Methods -

- Interface Materials -

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Useful Links

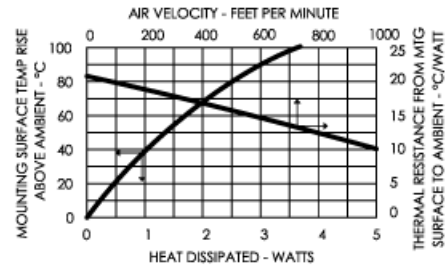
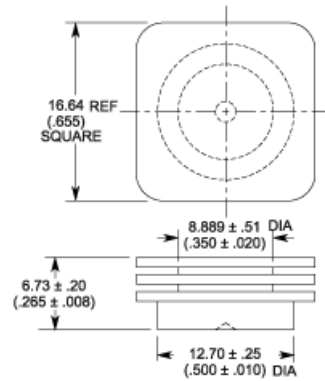
- [Building a part #](#)
- [Catalog Request](#)
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- [MSDS Safety Sheets](#)
- [Part # Cross Ref](#)
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Products / BGA / Radial Fins

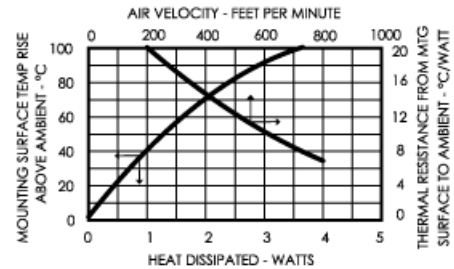
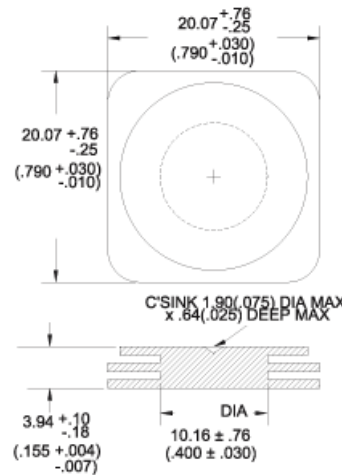
Radial Fin Heat Sinks for Microprocessors

- Bond-on heat sinks for leadless chip carriers and flat packs.
- Primarily designed for 68-position devices.
- The 2283 is ideally suited to limited board space applications with high air flow.

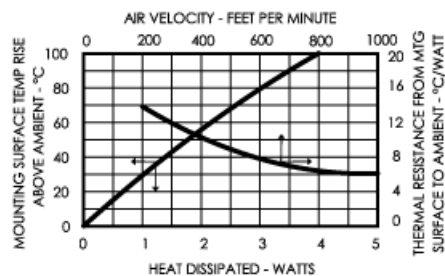
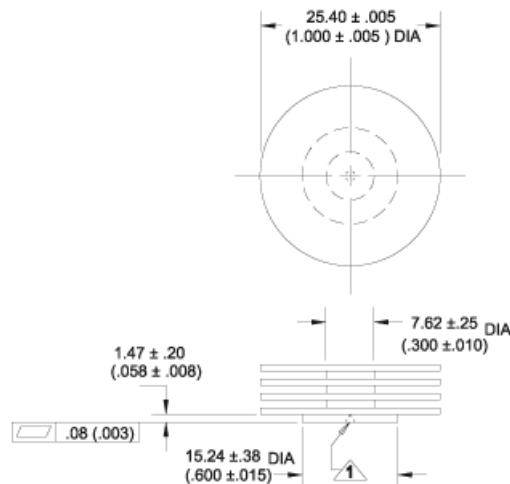
Part Number: 2283BG



Part Number: 2286BG<

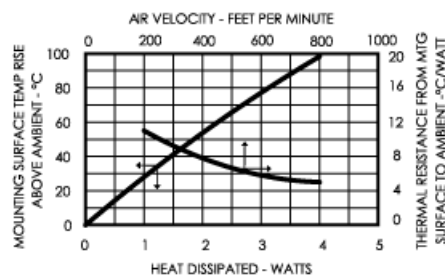
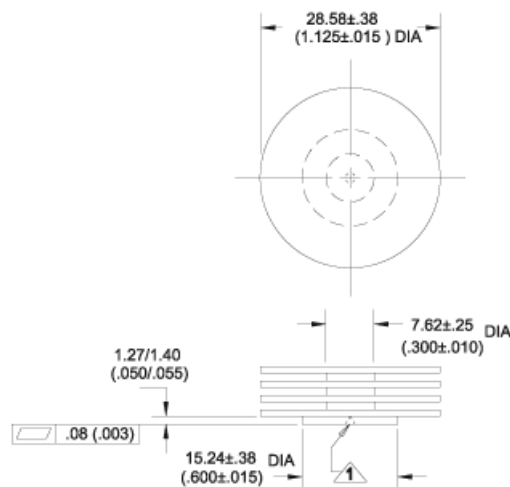


Part Number: 2288BG



Part Number: 2292BG

RoHS Compliant



Part Number: 2296BG



